Title (en)

Epoxy resin encapsulation compositions

Title (de)

Epoxyharz Verkapselungszusammensetzung

Title (fr)

Compositions d'encapsulation à base des résines époxy

Publication

EP 1285938 B1 20060125 (EN)

Application

EP 02255685 A 20020814

Priority

US 93540901 A 20010823

Abstract (en)

[origin: EP1285938A1] Epoxy resin compositions are disclosed which comprise (A) at least one cycloaliphatic epoxy resin, (B) a curing agent comprising hexahydro-4-methylphthalic anhydride, (C) at least one a boron containing catalyst that is essentially free of halogen, and (D) at least one cure modifier. The encapsulant (11) may also optionally comprise at least one of ancillary curing catalysts, thermal stabilizers, UV stabilizers, coupling agents, or refractive index modifiers. Also disclosed are packaged solid state devices comprising a package, a chip (4), and an encapsulant (11) comprising an epoxy resin composition of the invention. A method of encapsulating a solid state device is also provided.

IPC 8 full level

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